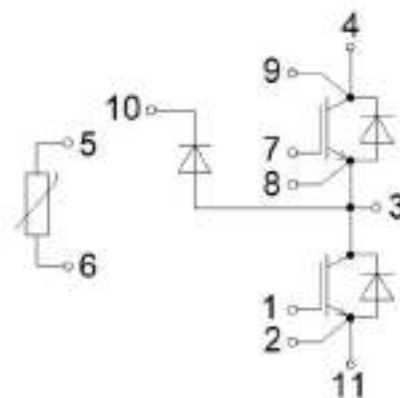


C5 series package: 1200V 450A IGBT module

[Datasheet](#)



Equivalent  
Circuit Schematic

## Features:

- Trenchgate Gen.7 IGBT technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High RBSOA capability
- Low static losses:  $V_{CE(sat)} = 1,5V@25^{\circ}C$
- Low dynamic losses

## Options:

- Pre-applied TIM (option +M01)
- Adoption for parallel connection ( $V_f$  selection)

## Typical Applications:

- 3L NPC inverters
- Motor drives
- Energy Storage

## IGBT, Inverter / IGBT

### Maximum Rated Values

Collector-emitter Voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	1200	V
Continuous DC Collector Current		$I_{Cnom}$	450	A
	$T_C = 100^{\circ}\text{C}, T_{vj\ max} \leq 175^{\circ}\text{C}$	$I_C$	500	A
Repetitive Peak Collector Current	$t_p\ T_{vj\ op}$	$I_{CRM}$	900	A
Total Power Dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	$P_{tot}$	2344	W
Gate-emitter Peak Voltage		$V_{GES}$	$\pm 20$	V

## Characteristic Values

		min. typ. max.			
Collector-emitter Saturation Voltage <sup>1)</sup>	$I_C = 450\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$V_{CESat}$	1.40	1.50 1.76 1.84	1.70 V
Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 24\text{mA}, T_{vj} = 25^{\circ}\text{C}$	$V_{GEth}$	5.0	6.0	7.0 V
Gate Charge	$V_{GE} = -10\text{V}/15\text{V}, V_{CE} = 600\text{V}$	$Q_G$	—	4.1	— $\mu\text{C}$
Internal Gate Resistor	$T_{vj} = 25^{\circ}\text{C}$	$R_{Gint}$	—	1.05	— $\Omega$
Input Capacitance	$f = 100\text{kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$C_{ies}$	—	106	— nF
Output Capacitance	$f = 100\text{kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$C_{oes}$	—	1.96	— nF
Reverse Transfer Capacitance	$f = 100\text{kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$C_{res}$	—	0.28	— nF
Collector-emitter Cutoff Current	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$	$I_{CES}$	—	—	100 $\mu\text{A}$
Gate-emitter Leakage Current	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$	$I_{GES}$	—	—	500 nA
Turn-on Delay Time, Inductive Load	$I_C = 450\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = -8\text{V}/15\text{V}$ $R_{GON} = 0.5\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$t_{don}$	—	186 192 195 217	— ns
Rise Time, Inductive Load	$I_C = 450\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = -8\text{V}/15\text{V}$ $R_{GON} = 0.5\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$t_r$	—	54 64 67 85	— ns
Turn-off Delay Time, Inductive Load	$I_C = 450\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = -8\text{V}/15\text{V}$ $R_{GON} = 1.0\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$t_{doff}$	—	435 485 492 553	— ns
Fall Time, Inductive Load	$I_C = 450\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = -8\text{V}/15\text{V}$ $R_{Goff} = 1\Omega$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$t_f$	—	123 191 203 210	— ns
Turn-on Energy Loss per Pulse	$I_C = 450\text{A}, V_{CE} = 600\text{V}, L_{\sigma} = 30\text{nH}$ $V_{GE} = -8\text{V}/15\text{V}, R_{gon} = 0.5\Omega$ $di/dt = 4200\text{A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$E_{on}$	—	18.4 27.5 31.2 35.0	— mJ
Turn-off energy Loss per Pulse	$I_C = 450\text{A}, V_{CE} = 600\text{V}, L_{\sigma} = 30\text{nH}$ $V_{GE} = -8\text{V}/15\text{V}, R_{goff} = 1.0\Omega$ $du/dt = 6300\text{V}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$E_{off}$	—	33.4 46.4 50.4 56.9	— mJ

SC Data	V <sub>GE</sub> = -8V/15V V <sub>CC</sub> = 600V  t <sub>p</sub> ≤ 10μs, T <sub>vj</sub> = 25°C t <sub>p</sub> ≤ 10μs, T <sub>vj</sub> = 150°C t <sub>p</sub> ≤ 10μs, T <sub>vj</sub> = 175°C	I <sub>sc</sub>	—	2700 2100 2000	—	A
Thermal Resistance, Junction to Case	Per IGBT / IGBT	R <sub>thJC</sub>	—	0.064	—	K/W
Thermal Resistance, Case to Heatsink	Per IGBT / IGBT λ <sub>grease</sub> = 1W/(m·K)	R <sub>thCH</sub>	—	0.019	—	K/W
Temperature under Switching Conditions		T <sub>vj op</sub>	-40		175	°C

## Diode, Inverter Maximum Rated Values

Repetitive Peak Reverse Voltage	T <sub>vj</sub> = 25°C	V <sub>RRM</sub>	1200	V
Continuous DC Forward Current		I <sub>Fnom</sub>	450	A
Repetitive Peak Forward Current	t <sub>p</sub> T <sub>vj op</sub>	I <sub>FRM</sub>	900	A

## Characteristic Values

			min.	typ.	max.	
Forward Voltage <sup>1)</sup>	I <sub>F</sub> = 450A, V <sub>GE</sub> = 0V  T <sub>vj</sub> = 25°C T <sub>vj</sub> = 150°C T <sub>vj</sub> = 175°C	V <sub>F</sub>	1.50	1.95 1.92 1.82	2.40	V
Peak Reverse Recovery Current	I <sub>F</sub> = 450A, V <sub>R</sub> = 600V -di <sub>F</sub> /dt = 5600A/μs (T <sub>vj</sub> = 175°C) V <sub>GE</sub> = -8V  T <sub>vj</sub> = 25°C T <sub>vj</sub> = 125°C T <sub>vj</sub> = 150°C T <sub>vj</sub> = 175°C	I <sub>RM</sub>	—	302 358 374 390	—	A
Recovery Charge	I <sub>F</sub> = 450A, V <sub>R</sub> = 600V -di <sub>F</sub> /dt = 5600A/μs (T <sub>vj</sub> = 175°C) V <sub>GE</sub> = -8V  T <sub>vj</sub> = 25°C T <sub>vj</sub> = 125°C T <sub>vj</sub> = 150°C T <sub>vj</sub> = 175°C	Q <sub>R</sub>	—	21.3 42.1 50.0 56.0	—	μC
Reverse Recovery Energy	I <sub>F</sub> = 450A, V <sub>R</sub> = 600V -di <sub>F</sub> /dt = 5600A/μs (T <sub>vj</sub> = 175°C) V <sub>GE</sub> = -8V  T <sub>vj</sub> = 25°C T <sub>vj</sub> = 125°C T <sub>vj</sub> = 150°C T <sub>vj</sub> = 175°C	E <sub>rec</sub>	—	11.3 22.5 27.7 33.0	—	mJ
Thermal Resistance, Junction to Case	Per FRD	R <sub>thJC</sub>	—	0.092	—	K/W
Thermal Resistance, Case to Heatsink	Per FRD λ <sub>grease</sub> = 1W/(m·K)	R <sub>thHC</sub>	—	0.021	—	K/W
Temperature under Switching Conditions <sup>2)</sup>		T <sub>vj op</sub>	-40	—	175	°C

## Diode, 3-Level Maximum Rated Values

Repetitive Peak Reverse Voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	1200	V
Continuous DC Forward Current		$I_{Fnom}$	450	A
Repetitive Peak Forward Current	$T_{vj\ op}$	$I_{FRM}$	900	A

## Characteristic Values

			min.	typ.	max.	
Forward Voltage <sup>1)</sup>	$I_F = 450\text{A}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$V_F$	1.50	1.95 1.92 1.82	2.40	V
Peak Reverse Recovery Current	$I_F = 450\text{A}, V_R = 600\text{V}$ $-di_F/dt = 5600\text{A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $V_{GE} = -8\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$I_{RM}$	—	302 358 374 390	—	A
Recovery Charge	$I_F = 450\text{A}, V_R = 600\text{V}$ $-di_F/dt = 5600\text{A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $V_{GE} = -8\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$Q_R$	—	21.3 42.1 50.0 56.0	—	$\mu\text{C}$
Reverse Recovery Energy	$I_F = 450\text{A}, V_R = 600\text{V}$ $-di_F/dt = 5600\text{A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $V_{GE} = -8\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	$E_{rec}$	—	11.3 22.5 27.7 33.0	—	mJ
Thermal Resistance, Junction to Case	Per FRD	$R_{thJC}$	—	0.092	—	K/W
Thermal Resistance, Case to Heatsink	Per FRD $\lambda_{grease} = 1\text{W}/(\text{m}\cdot\text{K})$	$R_{thHC}$	—	0.021	—	K/W
Temperature under Switching Conditions <sup>2)</sup>		$T_{vj\ op}$	-40	—	175	$^{\circ}\text{C}$

## NTC-Thermistor / NTC Maximum Rated Values

			min.	typ.	max.	
Rated Resistance	$T_{NTC} = 25^{\circ}\text{C}$	$R_{25}$	—	5	—	K $\Omega$
Deviation of R100 R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 491\Omega$	$\Delta R/R$	-5	—	5	%
Power Dissipation	$T_{NTC} = 25^{\circ}\text{C}$	$P_{25}$	—	—	20	mW
B-Value	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15\text{K}))]$	$B_{25/50}$	—	3375	—	K
	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15\text{K}))]$	$B_{25/80}$	—	3425	—	K
	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298.15\text{K}))]$	$B_{25/100}$	—	3443	—	K

1) Terminal impedance is not included.

2)  $T_{vj\ op} > 150^{\circ}\text{C}$  is allowed for operation at overload conditions.  
 $T_{vj\ op} > 150^{\circ}\text{C}$ .

## Module

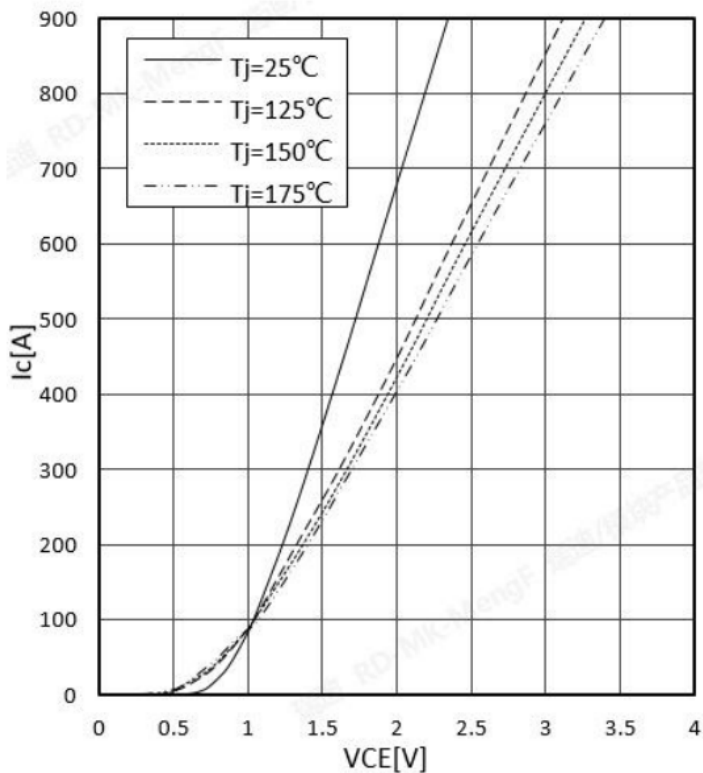
Isolation Test Voltage	RMS, f=50Hz	V <sub>ISOL</sub>	3.0	kV
Isolation Test Voltage of NTC NTC	RMS, f=50Hz	V <sub>ISOL</sub> (NTC)	3.0	kV
Material of Module Baseplate			Cu	
Internal Isolation			ZTA	
Creepage Distance	Terminal to heatsink, min Terminal to terminal, min		14.7 15.1	mm
Clearance	Terminal to heatsink, min Terminal to terminal, min		9.6 12.5	mm
Comparative Tracking Index		CTI	>200	

**min. typ. max.**

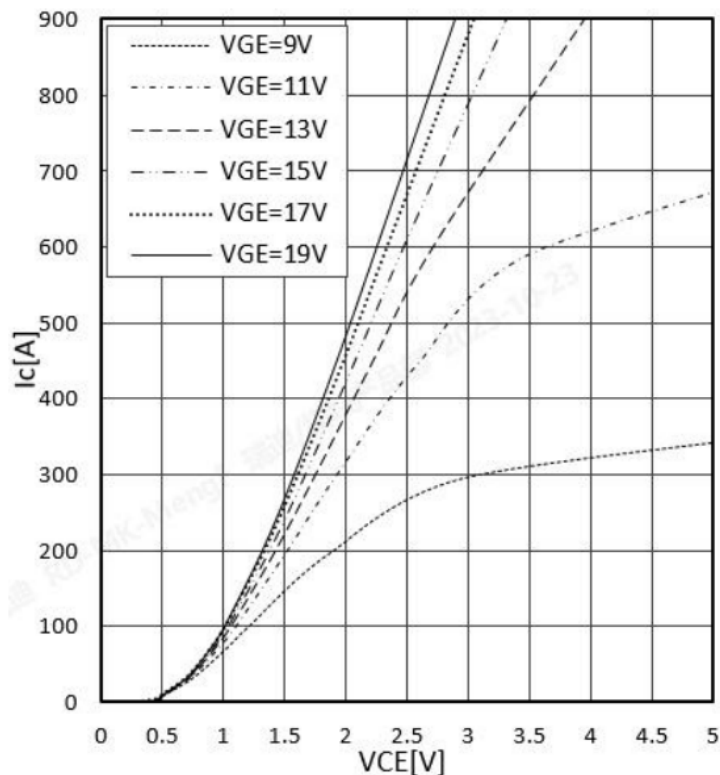
Stray Inductance Module		L <sub>sCE</sub>	—	20	—	nH
Module Lead Resistance, Terminals-Chip	T <sub>C</sub> = 25°C, Per Switch	R <sub>CC'+EE'</sub>	—	0.8	—	mΩ
Storage Temperature		T <sub>stg</sub>	-40	—	125	°C
Mounting Torque for Module Mounting	Screw M5 / M5	M	4.0	—	6.0	Nm
Mounting Torque for Terminal Mounting	Screw M6 / M6	M	4.0	—	6.0	Nm
Weight		G	—	345	—	g

## Circuit Diagram

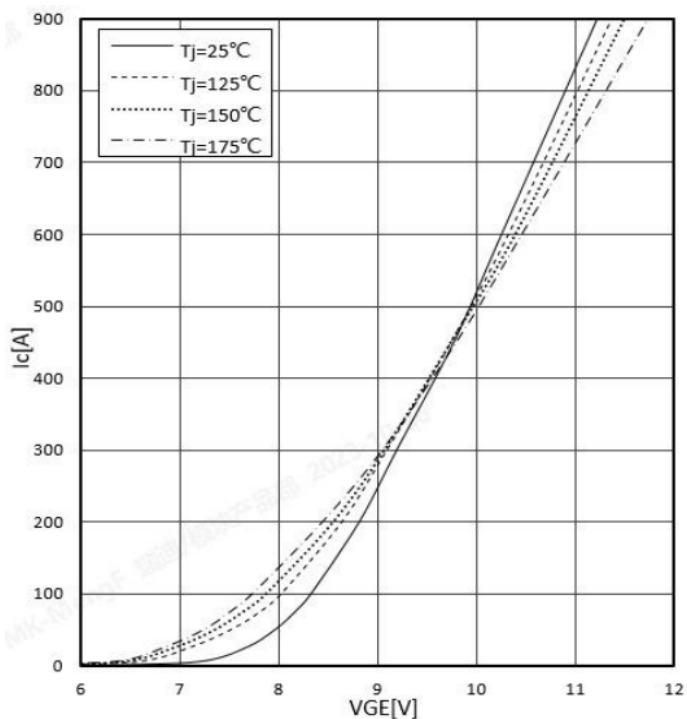
Output characteristic IGBT, Inverter (typical), IGBT  
 $I_c = f(V_{CE})$ ,  $V_{GE} = 15V$



Output characteristic IGBT, Inverter (typical), IGBT  
 $I_c = f(V_{CE})$ ,  $T_{vj} = 175^{\circ}C$

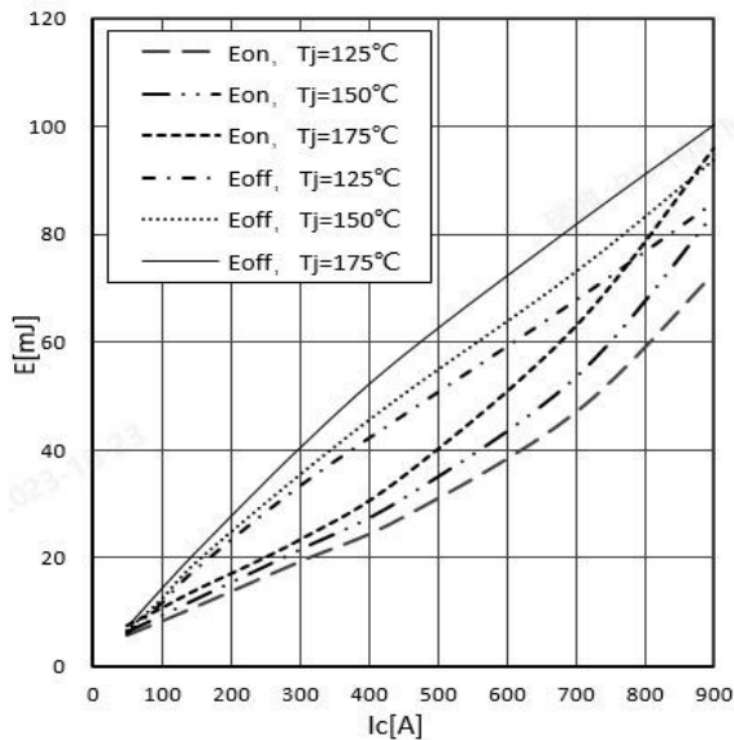


Transfer characteristic IGBT, Inverter (typical), IGBT  
 $I_c = f(V_{GE})$ ,  $V_{CE} = 20V$



Switching losses IGBT, Inverter (Typical), IGBT

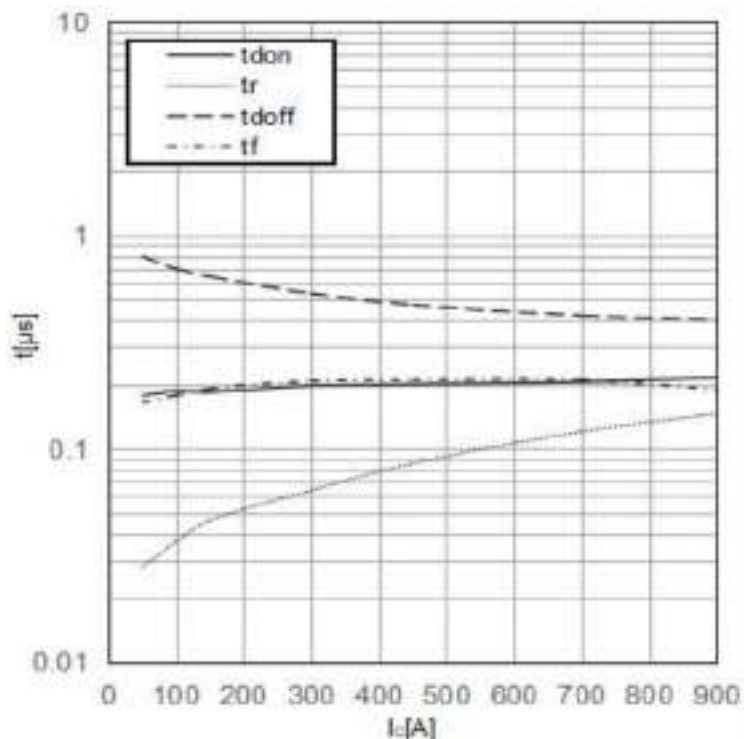
$E_{on} = f(I_c)$ ,  $E_{off} = f(I_c)$   
 $V_{GE} = +15V/-8V$ ,  $R_{Gon} = 0.5\Omega$ ,  $R_{Goff} = 1\Omega$ ,  $V_{CC} = 600V$



Switching time IGBT, Inverter (typical), IGBT

$t = f(I_C)$

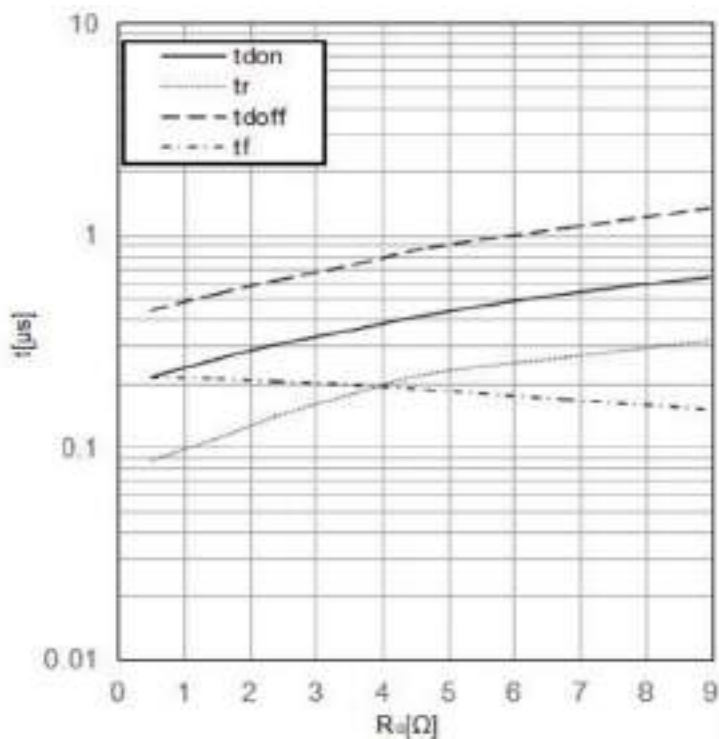
$R_{Goff} = 1\Omega$ ,  $R_{gon} = 0.5\Omega$ ,  $V_{GE} = +15V/-8V$ ,  $V_{CE} = 600V$ ,  $T_{vj} = 175^\circ C$



Switching time IGBT, Inverter (typical), IGBT

$t = f(R_G)$

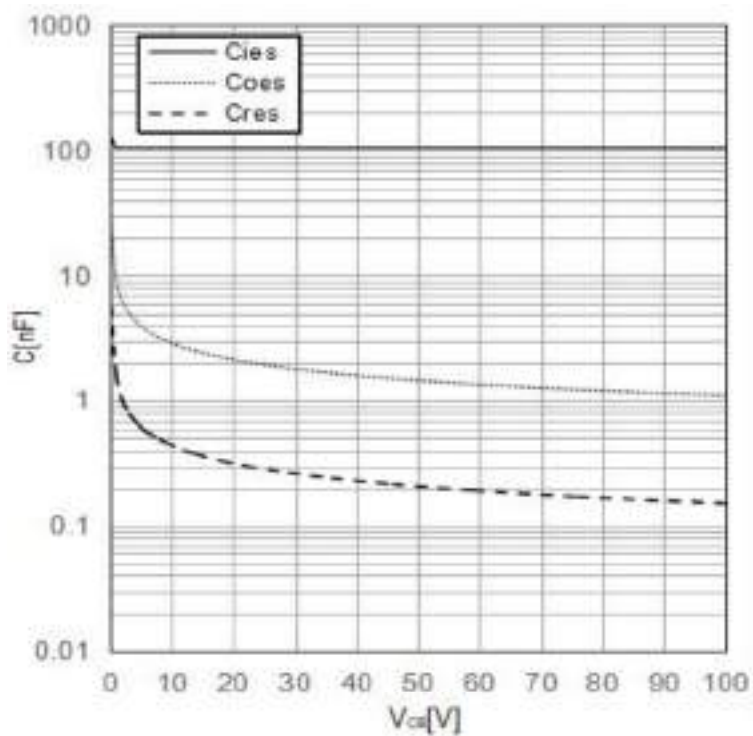
$V_{GE} = +15V/-8V$ ,  $I_C = 450A$ ,  $V_{CE} = 600V$ ,  $T_{vj} = 175^\circ C$



Capacitance characteristic IGBT, Inverter, IGBT

$C = f(V_{CE})$

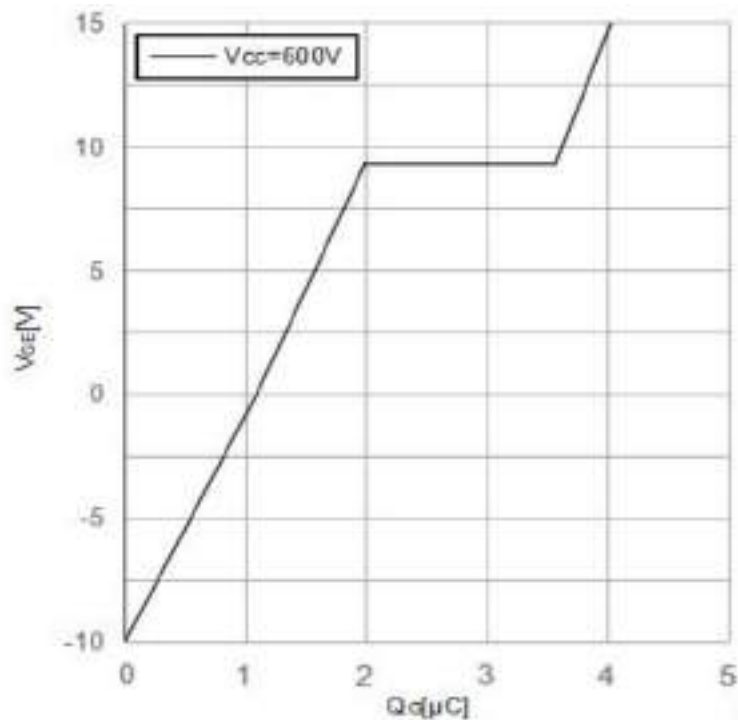
$f = 100kHz$ ,  $V_{GE} = 0V$ ,  $T_{vj} = 25^\circ C$



Gate Charge characteristic IGBT, Inverter, IGBT

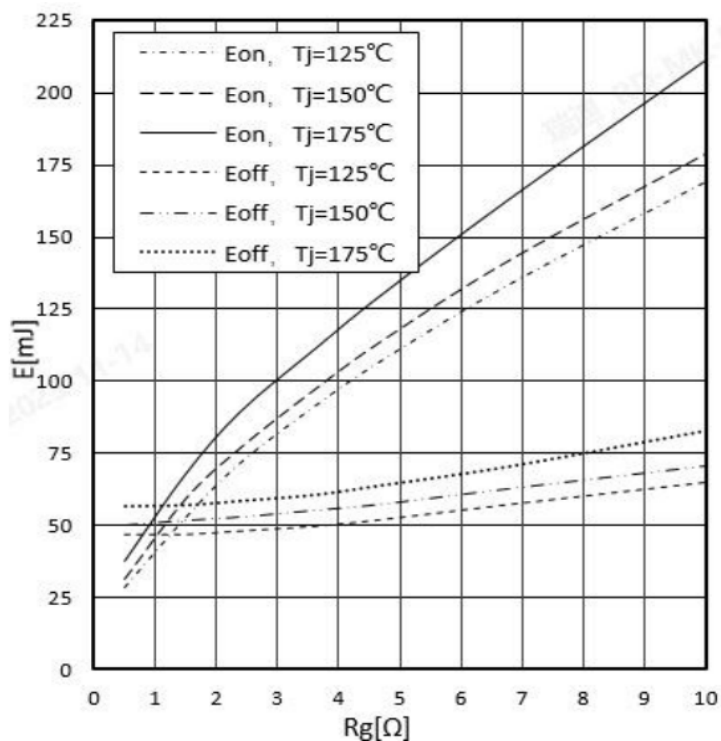
$V_{GE} = f(Q_G)$

$I_C = 450A$ ,  $T_{vj} = 25^\circ C$

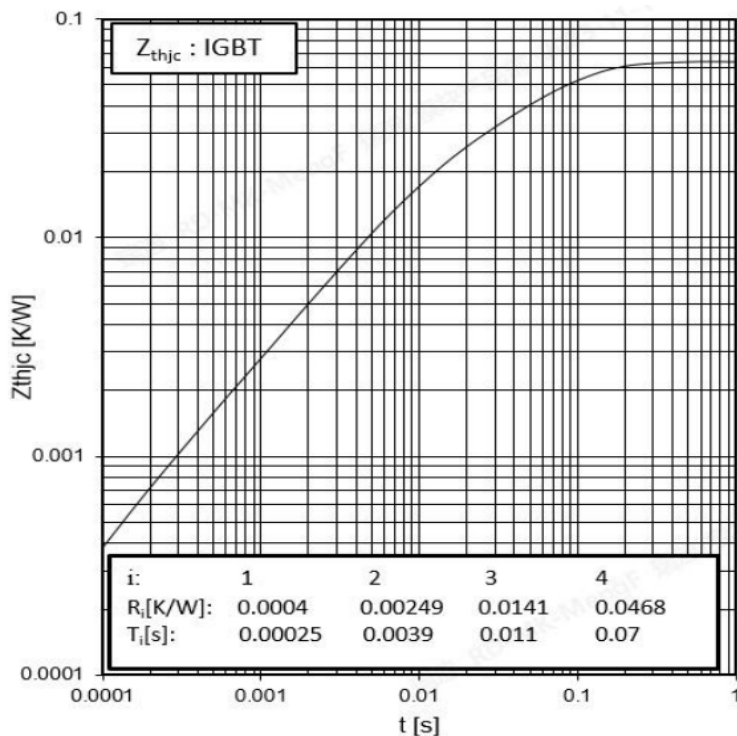




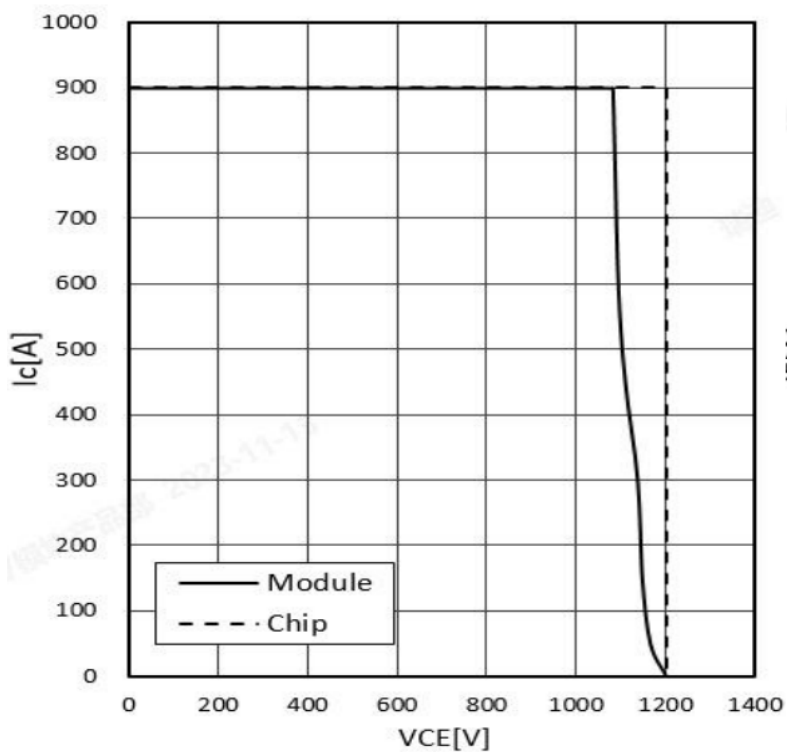
Switching losses IGBT, Inverter (Typical), IGBT  
 $E_{on} = f(R_g)1\Omega$ ,  $E_{off} = f(R_g)$ ,  
 $V_{GE} = +15V/-8V$ ,  $I_c = 450A$ ,  $V_{CE} = 600V$



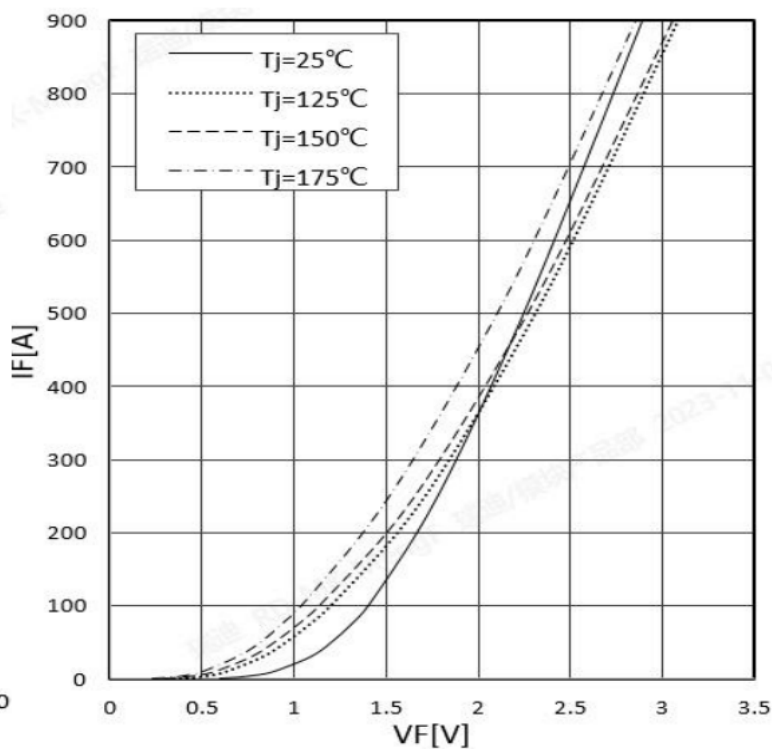
Transient thermal impedance IGBT, Inerter, IGBT  
 $E_{thjc} = f(t)$



Reverse bias safe operating area IGBT, Inverter (RBSOA)  
 IGBT (RBSOA)  
 $I_c = f(V_{CE})$   
 $V_{GE} = +15V/-8V$ ,  $R_{goff} = 1\Omega$ ,  $T_{vj} = 175^\circ C$



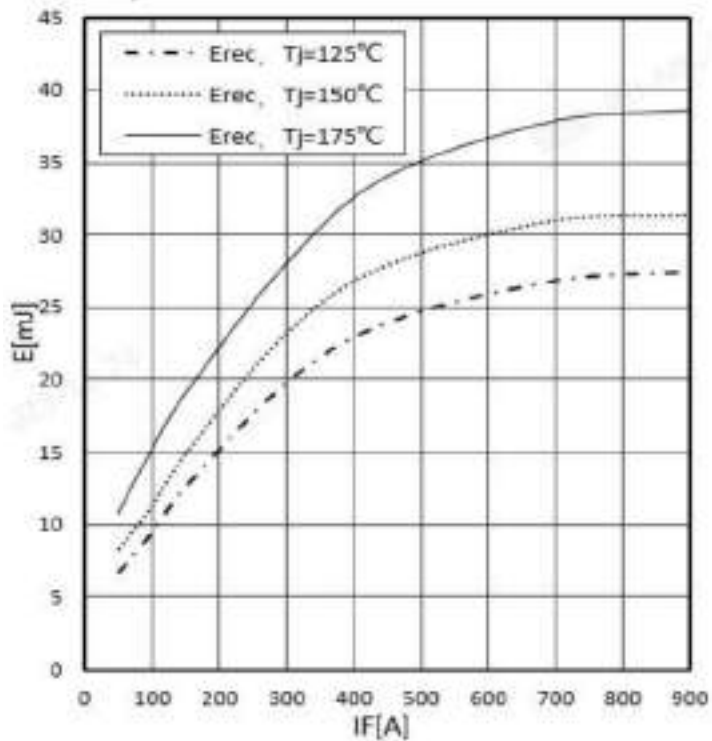
Forward characteristic of Diode, Inverter (typical)  
 $I_F = f(V_F)$





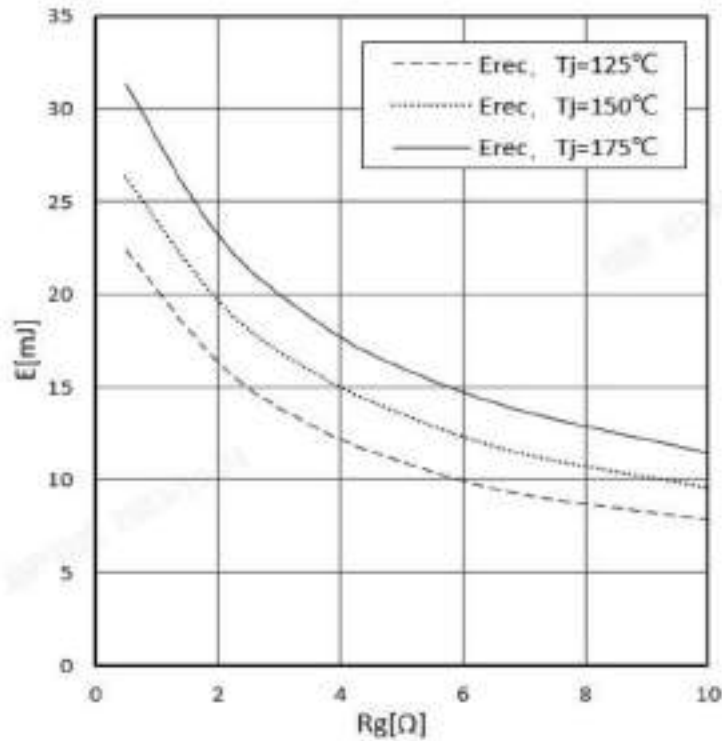
Switching losses Diode, Inverter (typical)

$$E_{rec} = f(I_F), R_{gon} = 0.5\Omega, V_{CE} = 600V$$



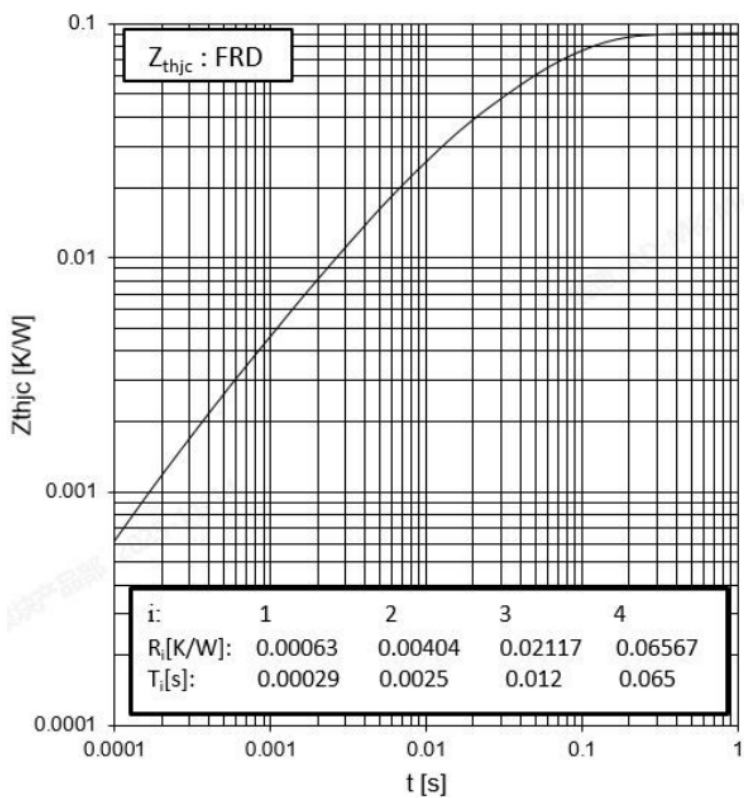
Switching losses Diode, Inverter (typical)

$$E_{rec} = f(R_G), I_F = 450A, V_{CE} = 600V$$



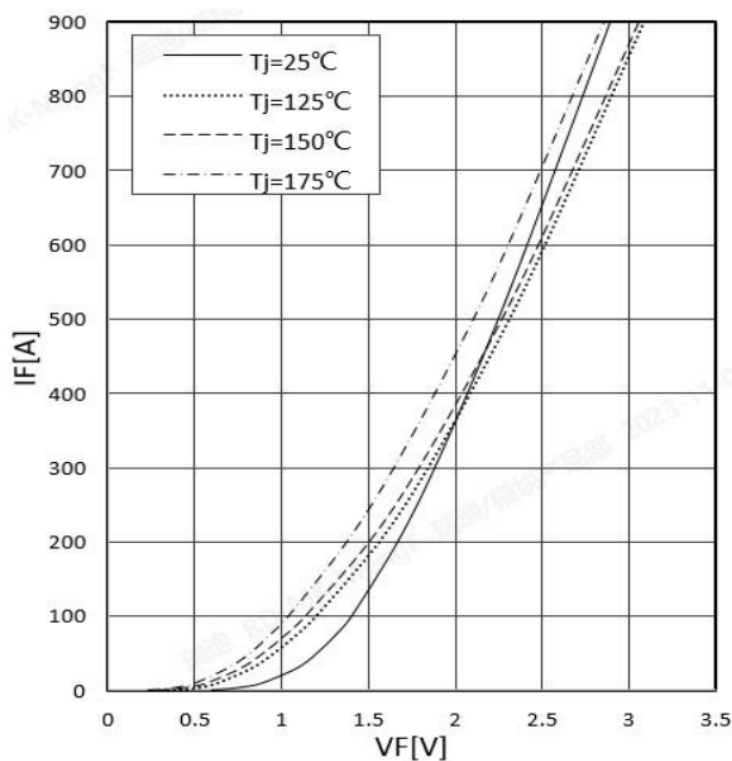
Transient thermal impedance Diode, Inverter

$$Z_{thJC} = f(t)$$

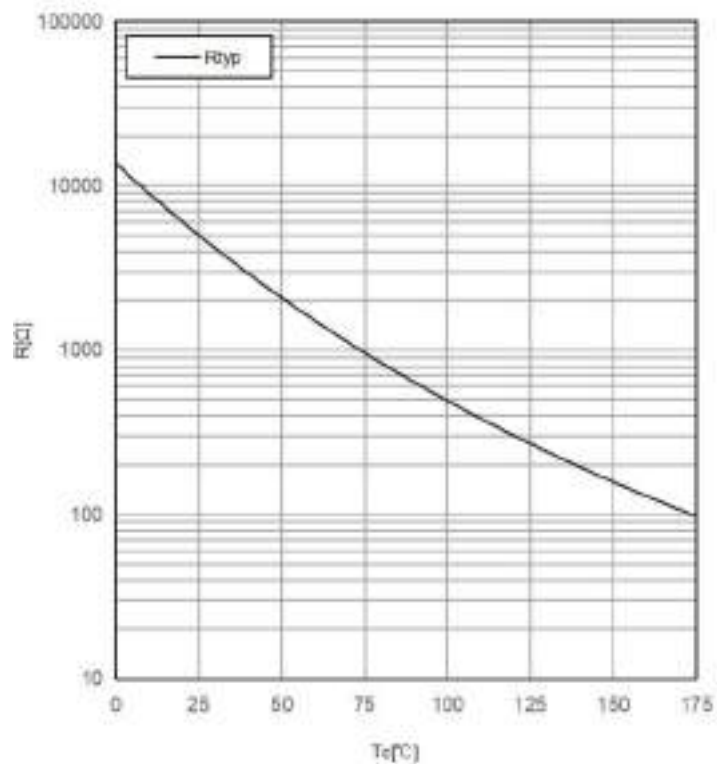


Forward characteristic of Diode, 3-Level (typical)

$$I_F = f(V_F)$$



NTC-Thermistor-temperature characteristic (typical)  
 $R = f(t)$



Technical drawing of a mechanical part, showing a top view (A) and a side view (B).

**Top View (A):** 1:1 scale. The part is a rectangular plate with rounded corners and a central octagonal hole. It features 12 mounting holes (6 on each long side) and 4 corner holes. Dimensions include overall width 152±0.5, overall height 62±0.5, and various hole diameters and positions.

**Side View (B):** Shows the thickness of the plate as 1.15±0.05. A section line A-A is indicated.

The circuit diagram shows a 10-bit DAC. It features a current mirror at the top with two input branches. The first branch has a resistor network connected to input 10, which is a 10-bit digital input. The second branch has a resistor network connected to input 9, which is a 9-bit digital input. The output of the current mirror is connected to input 8, which is an 8-bit digital input. The output of the current mirror is also connected to input 7, which is a 7-bit digital input. The output of the current mirror is also connected to input 6, which is a 6-bit digital input. The output of the current mirror is also connected to input 5, which is a 5-bit digital input. The output of the current mirror is also connected to input 4, which is a 4-bit digital input. The output of the current mirror is also connected to input 3, which is a 3-bit digital input. The output of the current mirror is also connected to input 2, which is a 2-bit digital input. The output of the current mirror is also connected to input 1, which is a 1-bit digital input. The output of the current mirror is also connected to input 11, which is a 11-bit digital input. The output of the current mirror is also connected to input 12, which is a 12-bit digital input. The output of the current mirror is also connected to input 13, which is a 13-bit digital input. The output of the current mirror is also connected to input 14, which is a 14-bit digital input. The output of the current mirror is also connected to input 15, which is a 15-bit digital input.

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